


MATERIAL DECLARATION SHEET



Material Number	PTVS6-076C-TH			
Product Line	Semiconductor Products			
Compliance Date	August 31 st 2013			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.373000	Bisphenol Epoxy Resin	1675-54-3	40.00	5.55	13.87
				Epoxy Resin	25085-99-8	20.00	2.77	
				Crystalline Silica	14464-46-1	23.00	3.19	
				Brominated Epoxy Resin	40039-93-8	12.00	1.66	
				Iron Oxide	51274-00-1	2.00	0.28	
				Titanium Oxide	13463-67-7	3.00	0.42	
2	Electrodes	Copper	1.444821	Copper	7440-50-8	99.10	53.22	53.71
				Silver	7440-22-4	0.40	0.21	
				Other	-	0.50	0.27	
3	Terminations	Copper	0.502942	Copper	7440-50-8	99.50	18.60	18.70
				Other	-	0.50	0.09	
4	Termination Finish	Silver	0.002178	Silver	7440-22-4	100.00	0.08	0.08
5	Chip	Silicon Die	0.159778	Silicon	7440-21-3	70.71	4.20	5.94
				Aluminium	7429-90-5	10.25	0.61	
				Nickel	7440-02-0	18.16	1.08	
				Gold	7440-57-5	0.88	0.05	
6	Die Attach	Solder	0.097978	Lead	7439-92-1	92.50	3.37	3.64
				Tin	7440-31-5	5.00	0.18	
				Silver	7440-22-4	2.50	0.09	
7	Die Coating	Silicone	0.109444	Polysiloxane	63148-62-9	22.11	0.90	4.07
				Chromium Sesquioxide	1308-38-9	5.67	0.23	
				Fumed Silica	112945-52-5	11.11	0.45	
				Filler	Trade Secret	61.11	2.49	
		Total Weight	2.690140					